



SOT263B

plastic single-ended package; heatsink mounted; 1 mounting hole; 5-lead TO-220

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-220-5
Package type industry code	TO-220-5
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	5-lead TO-220
Mounting method type	H (heatsink mount)
Issue date	11-1-2001

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		15.2	-	15.5	15.8	mm
E	package width		9.7	-	10	10.3	mm
A	seated height		4.1	-	4.3	4.5	mm
e	nominal pitch		-	-	1.7	-	mm
n ₂	actual quantity of termination		-	-	5	-	



2. Package outline

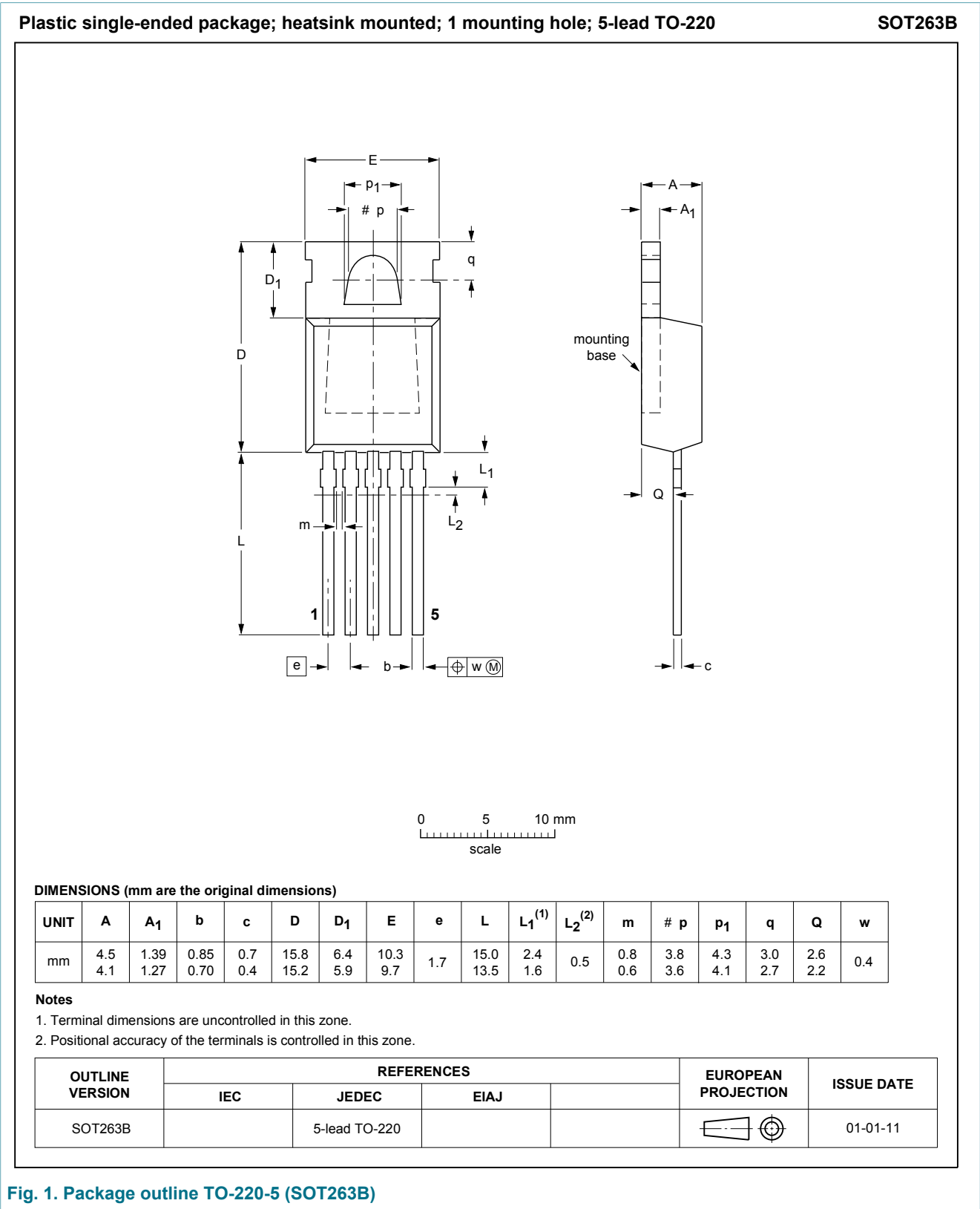


Fig. 1. Package outline TO-220-5 (SOT263B)

plastic single-ended package; heatsink mounted;
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3. Soldering

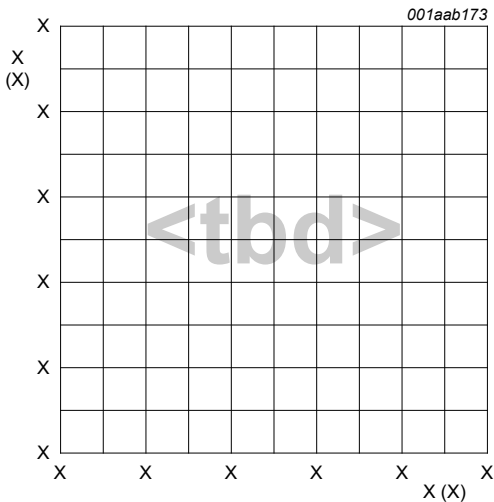


Fig. 2. Reflow soldering footprint for TO-220-5 (SOT263B)

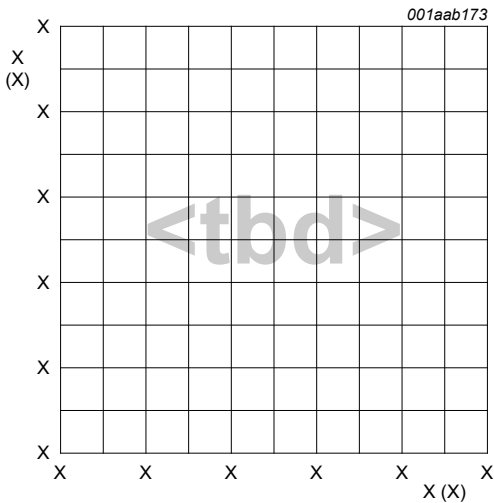


Fig. 3. Wave soldering footprint for TO-220-5 (SOT263B)

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4. Legal information

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